

# SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Part Number : **CL10C180FB8NNNC**
- Description : **CAP, 18pF, 50V, ±1%, COG, 0603**

## A. Samsung Part Number

CL  
①
10  
②
C  
③
180  
④
F  
⑤
B  
⑥
8  
⑦
N  
⑧
N  
⑨
N  
⑩
C  
⑪

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	0603 (inch code)	L: 1.6 ± 0.1 mm	W: 0.8 ± 0.1 mm
③ Dielectric	COG	⑧ Inner electrode	Ni
④ Capacitance	18 pF	Termination	Cu
⑤ Capacitance tolerance	± 1 %	Plating	Sn 100% (Pb Free)
⑥ Rated Voltage	50 V	⑨ Product	Normal
⑦ Thickness	0.8 ± 0.1 mm	⑩ Special	Reserved for future use
		⑪ Packaging	Cardboard Type, 7" reel

## B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1MHz±10%      0.5~5Vrms
Q	760 min	
Insulation Resistance	10,000Mohm or 500Mohm·μF Whichever is Smaller	Rated Voltage      60~120 sec.
Appearance	No abnormal exterior appearance	Microscope (×10)
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	300% of the rated voltage
Temperature Characterisitcs	COG (From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g·F, for 10±1 sec.
Bending Strength	Capacitance change : within ±5% or ±0.5pF whichever is larger	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 95% of terminal surface is to be soldered newly	1) Sn63Pb37 solder 235±5℃, 5±0.5sec. 2) SnAg3.0Cu0.5 solder 245±5℃, 3±0.3sec. (preheating : 80~120℃ for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within ±2.5% or ±0.25pF whichever is larger Tan δ, IR : initial spec.	Solder pot : 270±5℃, 10±1sec.

	<b>Performance</b>	<b>Test condition</b>
<b>Vibration Test</b>	Capacitance change : within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ whichever is larger Tan $\delta$ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours $\times$ 3 direction (x, y, z)
<b>Humidity</b>	Capacitance change : within $\pm 5\%$ or $\pm 0.5\text{pF}$ whichever is larger Q: 320 min IR : 1000Mohm or 50Mohm $\cdot \mu\text{F}$ Whichever is Smaller	40 $\pm$ 2 $^{\circ}\text{C}$ , 90~95%RH, 500+12/-0hrs
<b>Moisture Resistance</b>	Capacitance change : within $\pm 7.5\%$ or $\pm 0.75\text{pF}$ whichever is larger Q : 160 min IR : 500Mohm or 25Mohm $\cdot \mu\text{F}$ Whichever is Smaller	With rated voltage 40 $\pm$ 2 $^{\circ}\text{C}$ , 90~95%RH, 500+12/-0hrs
<b>High Temperature Resistance</b>	Capacitance change : within $\pm 3\%$ or $\pm 0.3\text{pF}$ whichever is larger Q : 320 min IR : 1000Mohm or 50Mohm $\cdot \mu\text{F}$ Whichever is Smaller	With 200% of the rated voltage Max. operating temperature 1000+48/-0hrs
<b>Temperature Cycling</b>	Capacitance change : within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ whichever is larger Tan $\delta$ , IR : initial spec.	1 cycle condition Min. operating temperature $\rightarrow$ 25 $^{\circ}\text{C}$ $\rightarrow$ Max. operating temperature $\rightarrow$ 25 $^{\circ}\text{C}$  5 cycle test

### C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 250 $\pm$ 5 $^{\circ}\text{C}$ , 6sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.